

Day : Tuesday  
 Date: 1/30/2007

Time: 12:23:59

**PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = TAKANISHI

First Name = KEIJIRO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<a href="#">07663958</a>	<a href="#">5153183</a>	150	05/06/1991	METHYLENEDIPHOSPHONIC ACID COMPOUNDS AND METHODS OF USE FO THE TREATMENT OF RHEUMATISM AND OSTEOPOROSIS	TAKANISHI, KEIJIRO
<a href="#">08256186</a>	<a href="#">5565440</a>	150	06/28/1994	METHANE DIPHOSPHONIC ACID DERIVATIVE, ITS PRODUCTION PROCESS AND ITS PHARMACEUTICAL APPLICATIONS	TAKANISHI, KEIJIRO
<a href="#">08555430</a>	<a href="#">5679481</a>	150	11/09/1995	CATHODE MATERIAL, METHOD OF PREPARING IT AND NONAQUEOUS SOLVENT TYPE SECONDARY BATTERY HAVING A CATHODE COMPRISING IT	TAKANISHI, KEIJIRO
<a href="#">08632421</a>	<a href="#">5886206</a>	150	07/02/1996	PROCESS FOR PRODUCTION OF METHANEDIPHOSPHONIC ACID COMPOUND	TAKANISHI, KEIJIRO
<a href="#">08936823</a>	Not Issued	161	09/25/1997	ELECTRODE FOR A BATTERY AND A BATTERY CONTAINING IT	TAKANISHI, KEIJIRO
<a href="#">10130643</a>	<a href="#">6750313</a>	150	05/20/2002	RESIN COMPOSITION AND ARTICLES MOLDED THEREFROM	TAKANISHI, KEIJIRO
<a href="#">10514886</a>	Not Issued	30	11/17/2004	Resin, resin composition, process for production thereof, and moldings made by using the same	TAKANISHI, KEIJIRO
<a href="#">10558275</a>	Not Issued	71	11/23/2004	Resin and article molded therefrom	TAKANISHI, KEIJIRO

Inventor Search Completed: No Records to Display.

Last Name

First Name

**Search Another: Inventor**

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Day : Tuesday  
Date: 1/30/2007

Time: 12:24:35

**PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = MATSUNO

First Name = TATSUYA

Application#	Patent#	Status	Date Filed	Title	Inventor Name
10514886	Not Issued	30	11/17/2004	Resin, resin composition, process for production thereof, and moldings made by using the same	MATSUNO, TATSUYA
10558275	Not Issued	71	11/23/2004	Resin and article molded therefrom	MATSUNO, TATSUYA

Inventor Search Completed: No Records to Display.

**Search Another: Inventor****Last Name****First Name**

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Day : Tuesday  
Date: 1/30/2007

Time: 12:25:10

**PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = KOHARA

First Name = TAKEHIRO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<a href="#">10558275</a>	Not Issued	71	11/23/2004	Resin and article molded therefrom	KOHARA, TAKEHIRO
<a href="#">11609724</a>	Not Issued	19	12/12/2006	ACRYLOYL MATERIALS FOR MOLDED PLASTICS	KOHARA, TAKEHIRO

Inventor Search Completed: No Records to Display.

**Search Another: Inventor****Last Name**

Kohara

**First Name**

Takehiro

**Search**

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FILE 'HOME' ENTERED AT 14:56:28 ON 30 JAN 2007

=> file pnttext  
COST IN U.S. DOLLARS  
  
FULL ESTIMATED COST

SINCE FILE ENTRY	TOTAL SESSION
0.21	0.21

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FILE 'PCTFULL' ENTERED AT 14:56:50 ON 30 JAN 2007  
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COPYRIGHT (C) 2007 Kenneth Mason Publications Ltd.

FILE 'USPATFULL' ENTERED AT 14:56:50 ON 30 JAN 2007  
CA INDEXING COPYRIGHT (C) 2007 AMERICAN CHEMICAL SOCIETY (ACS)

FILE 'USPAT2' ENTERED AT 14:56:50 ON 30 JAN 2007  
CA INDEXING COPYRIGHT (C) 2007 AMERICAN CHEMICAL SOCIETY (ACS)

=> s phosphonic acid and residue# and (divalent phenol residue# or dihydric phenol residue#)

5 FILES SEARCHED...

L1 10 PHOSPHONIC ACID AND RESIDUE# AND (DIVALENT PHENOL RESIDUE# OR  
DIHYDRIC PHENOL RESIDUE#)

=> s 11 and bicycloalkyl#  
L2 2 L1 AND BICYCLOALKYL#

=> d 12 1-2

L2 ANSWER 1 OF 2 EPFULL COPYRIGHT 2007 EPO/FIZ KA on STN

AN 2004:60209 EPFULL EDP 20050203 ED 20050203 UP 20050203  
DUPD 20050202 DUPW 200505

**TIEN RESIN AND ARTICLE MOLDED THEREFROM.**

TIER RESINE ET ARTICLE MOULE AVEC CETTE RESINE.

IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 5203031,  
IP:

MATSUNO, Tatsuya, 16-A2-33, Takehana Jizojiminamimachi, Yamashina-ku,  
Kyoto-shi, Kyoto 6078088, JP;  
INOUE, Emi, Toray Wakakusa-ryo 414 1-1, Oe 1-chome, Otsu-shi, Shiga  
5202141, JP;  
KOHARA, Takehiro, 10-A6-34, Sonoyama 2-chome, Otsu-shi, Shiga 5200842  
.JP

PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
Tokyo 103-8666, JP

PAN 203533

FAN 205555  
DT Patent

DI Fatene  
LAF Japanese

DAF Japanese  
LA English

LAP English  
 TL English; French  
 PIT WOAI International application published with search report  
 PI WO 2004106413 A1 20041209  
 DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO  
 SE SI SK TR  
 EXTENSION STATES: AL HR LT LV MK  
 AI EP 2004-745264 A 20040521  
 WO 2004-JP6953 A 20040521  
 PRAI JP 2003-148826 A 20030527  
 IC.VER 7  
 ICM C08G079-02  
 ICS G02B001-04  
  
 AN 2004:60209 EPFULL EDP 20050203 ED 20060329 UP 20060830  
 DUPD 20060830 DUPW 200635  
 TIEN RESIN AND ARTICLE MOLDED THEREFROM.  
 TIFR RESINE ET ARTICLE MOULE AVEC CETTE RESINE.  
 TIDE HARZ UND FORMKOeRPER DARAUS.  
 IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 5203031,  
 JP;  
 MATSUNO, Tatsuya, 16-A2-33, TakehanaJizojiminamimachi, Yamashina-ku,  
 Kyoto-shi, Kyoto 6078088, JP;  
 INOUE, Emi, Toray Wakakusa-ryo 4141-1, Oe 1-chome, Otsu-shi, Shiga  
 5202141, JP;  
 KOHARA, Takehiro, 10-A6-34, Sonoyama 2-chome, Otsu-shi, Shiga 5200842,  
 JP  
 PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
 Tokyo 103-8666, JP  
 PAN 203533  
 AG Kador & Partner, Corneliusstrasse 15, 80469 Muenchen, DE  
 AGN 100212  
 DT Patent  
 LAF Japanese  
 LA English  
 LAP English  
 TL German; English; French  
 PIT EPA1 Application published with search report  
 PI EP 1640405 A1 20060329  
 WO 2004106413 20041209  
 DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO  
 SE SI SK TR  
 AI EP 2004-745264 A 20040521  
 WO 2004-JP6953 A 20040521  
 PRAI JP 2003-148826 A 20030527  
 IPCI C08G0079-02 [I,A]; G02B0001-04 [I,A]  
 C08G0079-00 [I,C\*]; G02B0001-04 [I,C\*]  
  
 L2 ANSWER 2 OF 2 USPATFULL on STN  
 AN 2006:334849 USPATFULL  
 TI Resin and article molded therefrom  
 IN Takanishi, Keijiro, 10-22-1504, HESO 3-CHOME, RITTO-SHI, SHIGA, JAPAN  
 520-3031  
 Matsuno, Tatsuya, Kyoto, JAPAN  
 Inoue, Emi, Shiga, JAPAN  
 Kohara, Takehiro, Shiga, JAPAN  
 PI US 2006287464 A1 20061221  
 AI US 2004-558275 A1 20040521 (10)  
 WO 2004-JP6953 20040521  
 20041123 PCT 371 date  
 PRAI JP 2003-148826 20030527  
 DT Utility  
 FS APPLICATION  
 LN.CNT 847

INCL INCLM: 528/086.000  
INCLS: 528/398.000  
NCL NCLM: 528/086.000  
NCLS: 528/398.000  
IC IPCI C08G0061-02 [I,A]; C08G0061-00 [I,C\*]; C08G0079-02 [I,A];  
C08G0079-00 [I,C\*]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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L1 ANSWER 1 OF 10 EPFULL COPYRIGHT 2007 EPO/FIZ KA on STN  
  
AN 2004:60209 EPFULL EDP 20050203 ED 20050203 UP 20050203  
DUPD 20050202 DUPW 200505  
TIEN RESIN AND ARTICLE MOLDED THEREFROM.  
TIFR RESINE ET ARTICLE MOULE AVEC CETTE RESINE.  
IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 5203031,  
JP;  
MATSUNO, Tatsuya, 16-A2-33, Takehana Jizojiminamimachi, Yamashina-ku,  
Kyoto-shi, Kyoto 6078088, JP;  
INOUE, Emi, Toray Wakakusa-ryo 414 1-1, Oe 1-chome, Otsu-shi, Shiga  
5202141, JP;  
KOHARA, Takehiro, 10-A6-34, Sonoyama 2-chome, Otsu-shi, Shiga 5200842,  
JP  
PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
Tokyo 103-8666, JP  
PAN 203533  
DT Patent  
LAF Japanese  
LA English  
LAP English  
TL English; French  
PIT WOA1 International application published with search report  
PI WO 2004106413 A1 20041209  
DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO  
SE SI SK TR  
EXTENSION STATES: AL HR LT LV MK  
AI EP 2004-745264 A 20040521  
WO 2004-JP6953 A 20040521  
PRAI JP 2003-148826 A 20030527  
IC.VER 7  
ICM C08G079-02  
ICS G02B001-04  
  
AN 2004:60209 EPFULL EDP 20050203 ED 20060329 UP 20060830  
DUPD 20060830 DUPW 200635  
TIEN RESIN AND ARTICLE MOLDED THEREFROM.  
TIFR RESINE ET ARTICLE MOULE AVEC CETTE RESINE.  
TIDE HARZ UND FORMKOeRPER DARAUS.  
IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 5203031,  
JP;  
MATSUNO, Tatsuya, 16-A2-33, Takehana Jizojiminamimachi, Yamashina-ku,  
Kyoto-shi, Kyoto 6078088, JP;  
INOUE, Emi, Toray Wakakusa-ryo 4141-1, Oe 1-chome, Otsu-shi, Shiga  
5202141, JP;  
KOHARA, Takehiro, 10-A6-34, Sonoyama 2-chome, Otsu-shi, Shiga 5200842,  
JP  
PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
Tokyo 103-8666, JP  
PAN 203533  
AG Kador & Partner, Corneliusstrasse 15, 80469 Muenchen, DE  
AGN 100212  
DT Patent

LAF Japanese  
 LA English  
 LAP English  
 TL German; English; French  
 PIT EPA1 Application published with search report  
 PI EP 1640405 A1 20060329  
 WO 2004106413 20041209  
 DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO  
 SE SI SK TR  
 AI EP 2004-745264 A 20040521  
 WO 2004-JP6953 A 20040521  
 PRAI JP 2003-148826 A 20030527  
 IPCI C08G0079-02 [I,A]; G02B0001-04 [I,A]  
 C08G0079-00 [I,C\*]; G02B0001-04 [I,C\*]  
 L1 ANSWER 2 OF 10 EPFULL COPYRIGHT 2007 EPO/FIZ KA on STN  
 AN 2003:53662 EPFULL  
 DUPD 20040121 DUPW 200404  
 TIEN RESIN, RESIN COMPOSITIONS, PROCESS FOR PRODUCTION THEREOF, AND MOLDINGS  
 MADE BY USING THE SAME.  
 TIFR RESINE, COMPOSITIONS DE RESINE, PROCEDE DE PRODUCTION ASSOCIE ET  
 MOULAGES CORRESPONDANTS.  
 IN MATSUNO, Tatsuya, 16-A2-33, Takehana Jizojiminamimachi, Yamashina-ku,  
 Kyoto-shi, Kyoto 607-8088, JP;  
 TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 520-3031,  
 JP  
 PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
 Tokyo 103-8666, JP  
 PAN 203533  
 DT Patent  
 LAF Japanese  
 LA English  
 LAP English  
 TL English; French  
 PIT WOA1 International application published with search report  
 PI WO 2003097720 A1 20031127  
 DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL  
 EXTENSION STATES: AL LT LV MK  
 AI EP 2003-721105 A 20030513  
 WO 2003-JP5946 A 20030513  
 PRAI JP 2002-144184 A 20020520  
 IC.VER 7  
 ICM C08G079-02  
 ICS C08L085-02; G02B001-04  
 AN 2003:53662 EPFULL ED 20050330 UP 20050907  
 DUPD 20050907 DUPW 200536  
 TIEN RESIN, RESIN COMPOSITIONS, PROCESS FOR PRODUCTION THEREOF, AND MOLDINGS  
 MADE BY USING THE SAME.  
 TIFR RESINE, COMPOSITIONS DE RESINE, PROCEDE DE PRODUCTION ASSOCIE ET  
 MOULAGES CORRESPONDANTS.  
 TIDE HARZ, HARZZUSAMMENSENZUNGEN, HERSTELLUNGSVERFAHREN DAFUEr UND DAMIT  
 HERGESTELLTE FORMKOeRPER.  
 IN MATSUNO, Tatsuya, 16-A2-33, Takehana Jizojiminamimachi, Yamashina-ku,  
 Kyoto-shi, Kyoto 607-8088, JP;  
 TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-shi, Shiga 520-3031,  
 JP  
 PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
 Tokyo 103-8666, JP  
 PAN 203533  
 AG Kador & Partner, Corneliusstrasse 15, 80469 Muenchen, DE  
 AGN 100211  
 DT Patent

LAF Japanese  
LA English  
LAP English  
TL German; English; French  
PIT EPA1 Application published with search report  
PI EP 1518884 A1 20050330  
WO 2003097720 20031127  
DS DE FR GB  
AI EP 2003-721105 A 20030513  
WO 2003-JP5946 A 20030513  
PRAI JP 2002-144184 A 20020520  
IC.VER 7  
ICM C08G079-02  
ICS C08L085-02; G02B001-04

L1 ANSWER 3 OF 10 EPFULL COPYRIGHT 2007 EPO/FIZ KA on STN

AN 2001:117271 EPFULL  
DUPD 20021016 DUPW 200242

TIEN RESIN COMPOSITION AND ARTICLES MOLDED THEREFROM.  
TIFR COMPOSITION DE RESINE ET ARTICLES MOULES A PARTIR DE CELLE-CI.  
TIDE HARZZUSAMMENSETZUNG UND DARAUS GEFORMTE ARTIKEL.  
IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-cho, Kurita-gun,  
Shiga 520-3031, JP;  
KUMAGAI, Takuya, Toray Mishima-ryo F532, 12-6, Bunkyo-cho 2-chome,  
Mishima-shi, Shizuoka 411-0033, JP;  
ISHINABE, Ryouichi, Seien-ryo 111, 15-1, Sonoyama 2-chome, Otsu-shi,  
Shiga 520-0842, JP

PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
Tokyo 103-8666, JP

PAN 203533

AG Kador & Partner, Corneliusstrasse 15, 80469 Muenchen, DE

AGN 100211

DT Patent

LAF Japanese

LA English

LAP English

TL German; English; French

PIT WO1 International application published with search report

PI WO 2002024787 A1 20020328

DS AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

AI EP 2001-963472 A 20010906  
WO 2001-JP7735 A 20010906

PRAI JP 2000-288254 A 20000922

IC.VER 7  
ICM C08G079-02  
ICS C08G064-08; C08J005-00; G02B001-04; G02B005-30

AN 2001:117271 EPFULL  
DUPD 20031203 DUPW 200349

TIEN RESIN COMPOSITION AND ARTICLES MOLDED THEREFROM.  
TIFR COMPOSITION DE RESINE ET ARTICLES MOULES A PARTIR DE CELLE-CI.  
TIDE HARZZUSAMMENSETZUNG UND DARAUS GEFORMTE ARTIKEL.  
IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-cho, Kurita-gun,  
Shiga 520-3031, JP;  
KUMAGAI, Takuya, 503-1-302, Yatamikado, Mishima-shi, Shizuoka 411-0801,  
JP;  
ISHINABE, Ryouichi, Seien-ryo 111, 15-1, Sonoyama 2-chome, Otsu-shi,  
Shiga 520-0842, JP

PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
Tokyo 103-8666, JP

PAN 203533

AG Kador & Partner, Corneliusstrasse 15, 80469 Muenchen, DE

AGN 100211

DT Patent  
 LAF Japanese  
 LA English  
 LAP English  
 TL German; English; French  
 PIT EPA1 Application published with search report  
 PI EP 1270646 A1 20030102  
 WO 2002024787 20020328  
 DS AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR  
 AI EP 2001-963472 A 20010906  
 WO 2001-JP7735 A 20010906  
 PRAI JP 2000-288254 A 20000922  
 IC.VER 7  
 ICM C08G079-02  
 ICS C08G064-08; C08J005-00; G02B001-04; G02B005-30  
  
 L1 ANSWER 4 OF 10 PCTFULL COPYRIGHT 2007 Univentio on STN  
 AN 2002024787 PCTFULL ED 20020701 EW 200213  
 TIEN RESIN COMPOSITION AND ARTICLES MOLDED THEREFROM  
 TIFR COMPOSITION DE RESINE ET ARTICLES MOULES A PARTIR DE CELLE-CI  
 IN TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-cho, Kurita-gun,  
     Shiga 520-3031, JP [JP, JP];  
     KUMAGAI, Takuya, Toray Mishima-ryo F532, 12-6, Bunkyo-cho 2-chome,  
     Mishima-shi, Shizuoka 411-0033, JP [JP, JP];  
     ISHINABE, Ryouichi, Seien-ryo 111, 15-1, Sonoyama 2-chome, Otsu-shi,  
     Shiga 520-0842, JP [JP, JP]  
 PA TORAY INDUSTRIES, INC., 2-1, Nihonbashi Muromachi 2-chome, Chuo-ku,  
     Tokyo 103-8666, JP [JP, JP], for all designates States except US;  
     TAKANISHI, Keijiro, 10-22-1504, Heso 3-chome, Ritto-cho, Kurita-gun,  
     Shiga 520-3031, JP [JP, JP], for US only;  
     KUMAGAI, Takuya, Toray Mishima-ryo F532, 12-6, Bunkyo-cho 2-chome,  
     Mishima-shi, Shizuoka 411-0033, JP [JP, JP], for US only;  
     ISHINABE, Ryouichi, Seien-ryo 111, 15-1, Sonoyama 2-chome, Otsu-shi,  
     Shiga 520-0842, JP [JP, JP], for US only  
 AG SATO, Kenji, c/o Shiga Branch, TORAY INTELLECTUAL PROPERTY EXPERTS CO.,  
     LTD., 1-1, Sonoyama 1-chome, Otsu-shi, Shiga 520-8558, JP  
 LAF Japanese  
 LA Japanese  
 DT Patent  
 PI WO 2002024787 A1 20020328  
 DS W: KR US  
     RW (EPO): AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE TR  
 PRAI JP 2000-2000-288254 20000922  
 AI WO 2001-JP7735 A 20010906  
 ICM C08G079-02  
 ICS C08G064-08; C08J005-00; G02B001-04; G02B005-30  
  
 L1 ANSWER 5 OF 10 USPATFULL on STN  
 AN 2006:334849 USPATFULL  
 TI Resin and article molded therefrom  
 IN Takanishi, Keijiro, 10-22-1504, HESO 3-CHOME, RITTO-SHI, SHIGA, JAPAN  
     520-3031  
     Matsuno, Tatsuya, Kyoto, JAPAN  
     Inoue, Emi, Shiga, JAPAN  
     Kohara, Takehiro, Shiga, JAPAN  
 PI US 2006287464 A1 20061221  
 AI US 2004-558275 A1 20040521 (10)  
     WO 2004-JP6953 20040521  
                         20041123 PCT 371 date  
 PRAI JP 2003-148826 20030527  
 DT Utility  
 FS APPLICATION  
 LN.CNT 847  
 INCL INCLM: 528/086.000

NCL INCLS: 528/398.000  
NCLM: 528/086.000  
NCLS: 528/398.000  
IC IPCI C08G0061-02 [I,A]; C08G0061-00 [I,C\*]; C08G0079-02 [I,A];  
C08G0079-00 [I,C\*]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L1 ANSWER 6 OF 10 USPATFULL on STN  
AN 2006:54799 USPATFULL  
TI Resin, resin composition, process for production thereof, and moldings made by using the same  
IN Matsuno, Tatsuya, Kyoto-shi, Kyoto, JAPAN  
Takanishi, Keijiro, Ritto-shi, Shiga, JAPAN  
PI US 2006047104 A1 20060302  
AI US 2003-514886 A1 20030513 (10)  
WO 2003-JP5946 20030513  
20041117 PCT 371 date  
PRAI JP 2002-144184 20020520  
DT Utility  
FS APPLICATION  
LN.CNT 1333  
INCL INCLM: 528/377.000  
NCL NCLM: 528/377.000  
IC IPCI C08G0075-32 [I,A]; C08G0075-00 [I,C\*]  
IPCR C08G0075-00 [I,C]; C08G0075-32 [I,A]; C08G0079-00 [I,C\*];  
C08G0079-02 [I,A]; C08L0085-00 [I,C\*]; C08L0085-02 [I,A];  
G02B0001-04 [I,C\*]; G02B0001-04 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L1 ANSWER 7 OF 10 USPATFULL on STN  
AN 2003:18079 USPATFULL  
TI Resin composition and articles molded therefrom  
IN Takanishi, Keijiro, Shiga, JAPAN  
Kumagai, Takuya, Shizuoka, JAPAN  
Ishinabe, Ryouichi, Shiga, JAPAN  
PI US 2003013836 A1 20030116  
US 6750313 B2 20040615  
AI US 2002-130643 A1 20020520 (10)  
WO 2001-JP7735 20010906  
PRAI JP 2000-288254 20000922  
DT Utility  
FS APPLICATION  
LN.CNT 943  
INCL INCLM: 528/086.000  
INCLS: 528/106.000; 528/108.000  
NCL NCLM: 528/196.000; 528/086.000  
NCLS: 264/176.100; 264/219.000; 359/642.000; 428/411.100; 428/412.000;  
528/198.000; 528/106.000; 528/108.000  
IC [7]  
ICM C08G065-40  
IPCI C08G0065-40 [ICM,7]; C08G0065-00 [ICM,7,C\*]  
IPCI-2 C08G0064-00 [ICM,7]  
IPCR C08G0064-00 [I,C\*]; C08G0064-08 [I,A]; C08G0079-00 [I,C\*];  
C08G0079-04 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L1 ANSWER 8 OF 10 USPATFULL on STN  
AN 94:51503 USPATFULL  
TI Process for preparing random copolycarbonate  
IN Marks, Maurice J., Lake Jackson, TX, United States  
Ho, Thoi H., Lake Jackson, TX, United States  
PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)  
PI US 5321116 19940614  
AI US 1993-43125 19930405 (8)

RLI Division of Ser. No. US 1991-730327, filed on 15 Jul 1991, now patented,  
Pat. No. US 5212282

DT Utility

FS Granted

LN.CNT 700

INCL INCLM: 528/204.000  
INCLS: 528/125.000; 528/126.000; 528/171.000; 528/174.000; 528/196.000;  
528/198.000; 528/201.000; 528/202.000

NCL NCLM: 528/204.000  
NCLS: 528/125.000; 528/126.000; 528/171.000; 528/174.000; 528/196.000;  
528/198.000; 528/201.000; 528/202.000

IC [5]  
ICM C08G064-20  
IPCI C08G0064-20 [ICM,5]; C08G0064-00 [ICM,5,C\*]  
IPCR C08G0064-00 [I,C\*]; C08G0064-06 [I,A]; C08G0064-20 [I,A]

EXF 528/204; 528/125; 528/126; 528/171; 528/174; 528/196; 528/198; 528/201;  
528/202

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L1 ANSWER 9 OF 10 USPATFULL on STN

AN 93:40105 USPATFULL

TI Process for preparing random copolycarbonate from dianion of  
ortho-substituted dihydric phenol

IN Marks, Maurice J., Lake Jackson, TX, United States  
Ho, Thoi H., Lake Jackson, TX, United States

PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)

PI US 5212282 19930518

AI US 1991-730327 19910715 (7)

DT Utility

FS Granted

LN.CNT 659

INCL INCLM: 528/204.000  
INCLS: 528/125.000; 528/126.000; 528/171.000; 528/174.000; 528/196.000;  
528/198.000; 528/201.000; 528/202.000

NCL NCLM: 528/204.000  
NCLS: 528/125.000; 528/126.000; 528/171.000; 528/174.000; 528/196.000;  
528/198.000; 528/201.000; 528/202.000

IC [5]  
ICM C08G064-20  
IPCI C08G0064-20 [ICM,5]; C08G0064-00 [ICM,5,C\*]  
IPCR C08G0064-00 [I,C\*]; C08G0064-06 [I,A]; C08G0064-20 [I,A]

EXF 528/204; 528/199; 528/196; 528/201; 528/202; 528/171; 528/174; 528/125;  
528/126

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L1 ANSWER 10 OF 10 USPAT2 on STN

AN 2003:18079 USPAT2

TI Resin composition and articles molded therefrom

IN Takanishi, Keijiro, Shiga, JAPAN  
Kumagai, Takuuya, Shizuoka, JAPAN  
Ishinabe, Ryouichi, Shiga, JAPAN

PA Toray Industries, Inc., JAPAN (non-U.S. corporation)

PI US 6750313 B2 20040615  
WO 2002024787 20020328

AI US 2002-130643 20020520 (10)  
WO 2001-JP7735 20010906

PRAI JP 2000-288254 20000922

DT Utility

FS GRANTED

LN.CNT 947

INCL INCLM: 528/196.000  
INCLS: 264/176.100; 264/219.000; 359/642.000; 428/411.100; 428/412.000;  
528/198.000

NCL NCLM: 528/196.000; 528/086.000

NCLS: 264/176.100; 264/219.000; 359/642.000; 428/411.100; 428/412.000;  
528/198.000; 528/106.000; 528/108.000

IC [7]

ICM C08G064-00

IPCI C08G0065-40 [ICM,7]; C08G0065-00 [ICM,7,C\*]

IPCI-2 C08G0064-00 [ICM,7]

IPCR C08G0064-00 [I,C\*]; C08G0064-08 [I,A]; C08G0079-00 [I,C\*];  
C08G0079-04 [I,A]

EXF 528/196; 528/198; 359/642; 428/411; 428/411.1; 428/412; 264/176.1;  
264/219

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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